



SOT1159-1

DFN3312-16: plastic thermal enhanced extremely thin small outline package; no leads; 16 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN3312-16
Package type industry code	DFN3312-16
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	17-12-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.2	-	3.3	3.4	mm
E	package width	1.1	-	1.2	1.3	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	16	-	

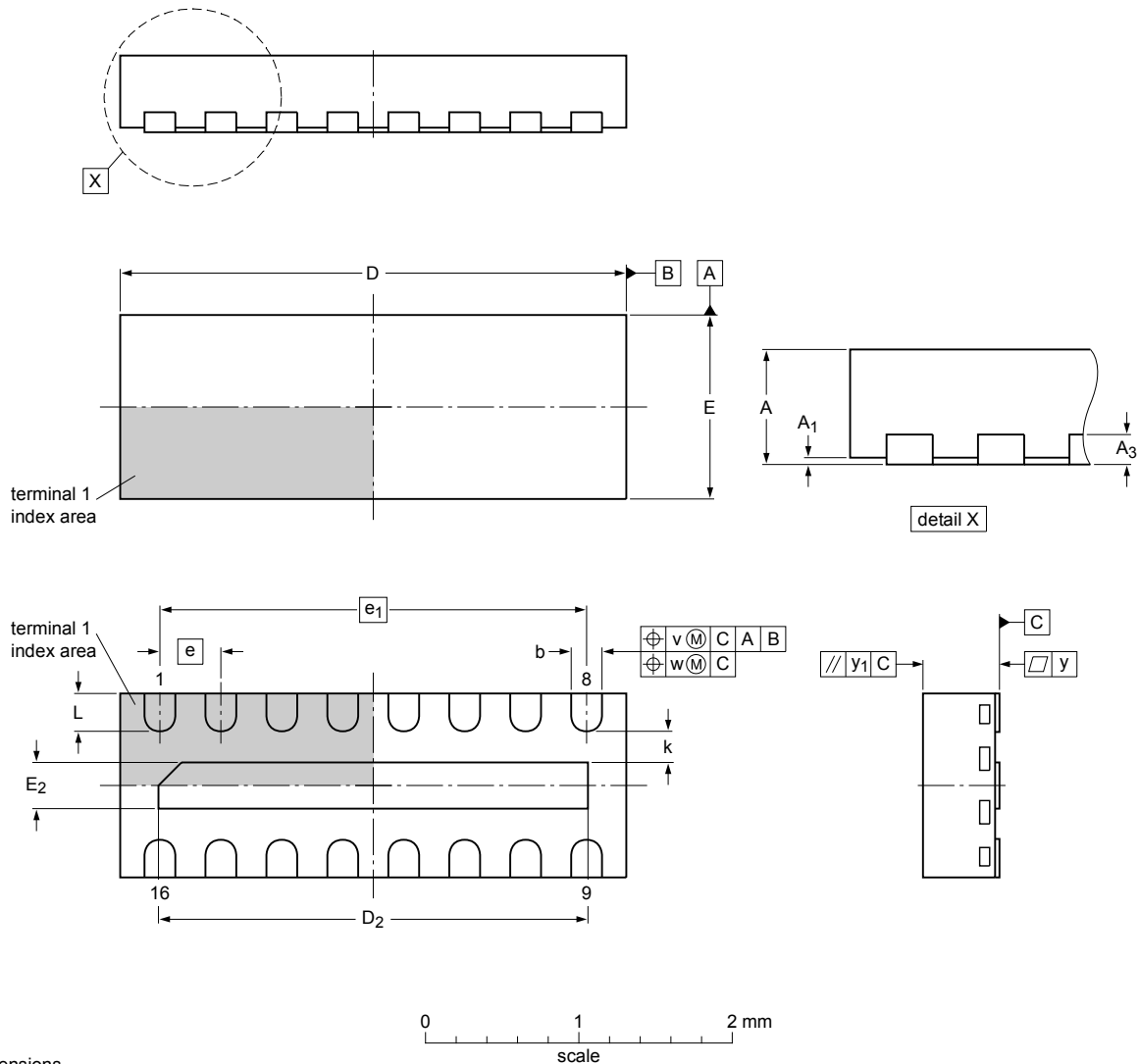


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2. Package outline

HXSON16: plastic thermal enhanced extremely thin small outline package; no leads; 16 terminals; body 1.2 x 3.3 x 0.5 mm

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Dimensions

Unit ⁽¹⁾	A	A ₁	A ₃	b	D	D ₂	E	E ₂	e	e ₁	k	L	v	w	y	y ₁
max	0.5	0.05		0.25	3.4	2.9	1.3	0.35				0.30				
mm nom			0.127	0.20	3.3	2.8	1.2	0.30	0.4	2.8	0.2	0.25	0.1	0.05	0.05	0.05
min		0.00		0.15	3.2	2.7	1.1	0.25				0.20				

Note

1. Plastic or metal protrusions of 0.075 maximum per side are not included.

sot1159-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1159-1	---	---	---		09-12-16 09-12-17

Fig. 1. Package outline DFN3312-16 (SOT1159-1)

3. Soldering

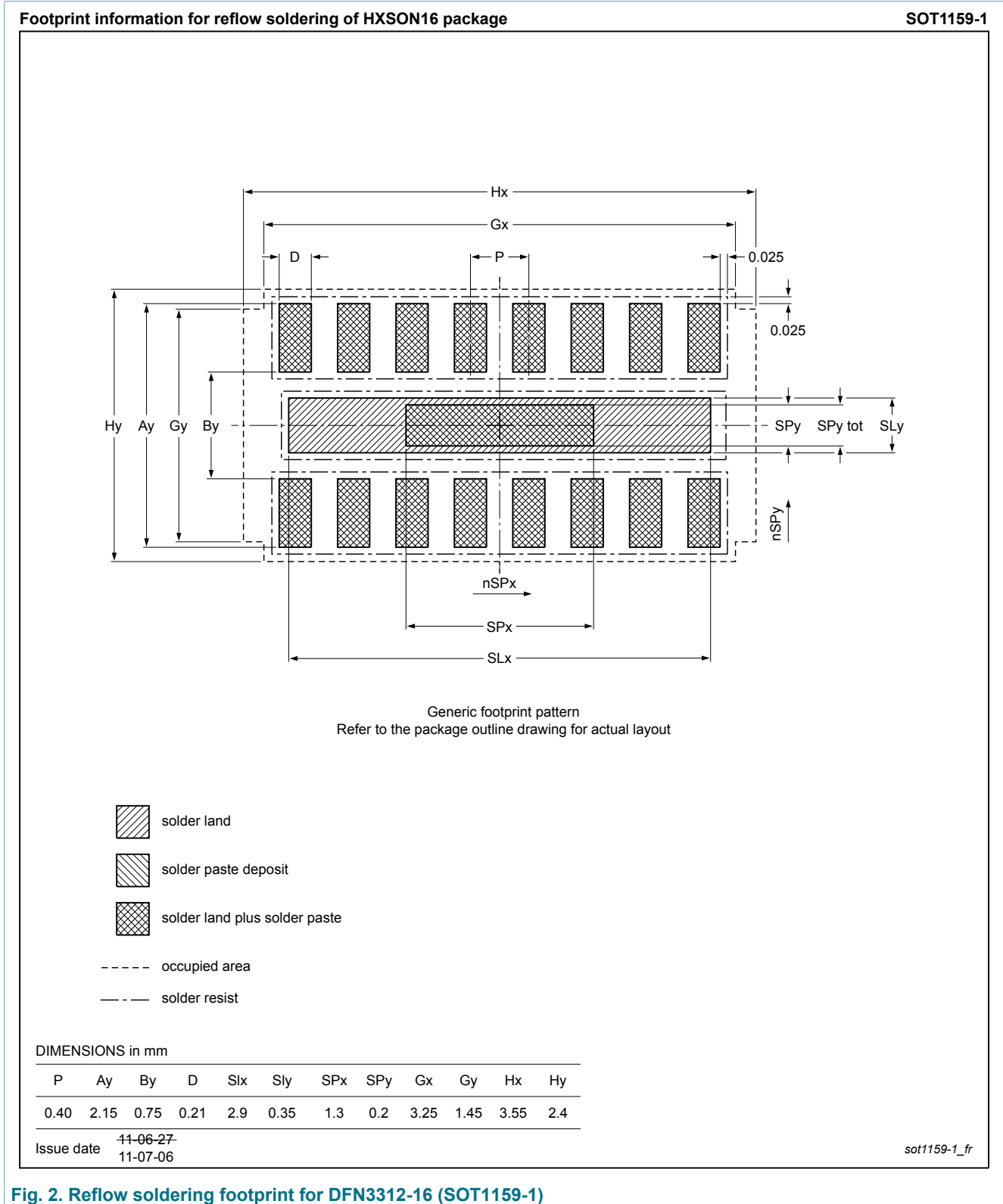


Fig. 2. Reflow soldering footprint for DFN3312-16 (SOT1159-1)

4. Legal information

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